

General Description

The LDS431L is a low voltage reference/ amplifier suited for the control loop of low voltage power supplies. Functionally similar to the ubiquitous TL431, the LDS431L has a lower 1.24V reference and a much wider range of operating currents. Particular care was taken in the design to minimize overshoot at startup and to allow wide AC bandwidth. The LDS431LP is a **drop-in replacement** for any 1.24V shunt reference.

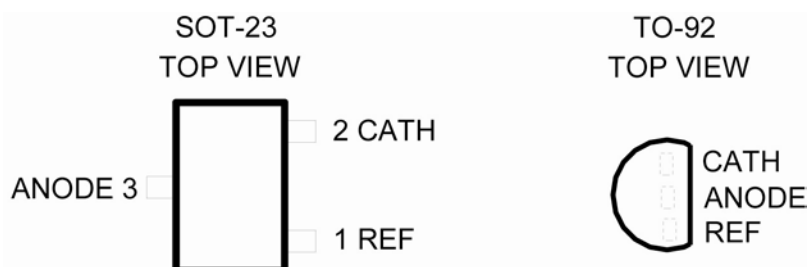
Applications

- Power supply control loop
- Low TC low voltage reference
- Power management applications

Features

- Low voltage reference: 1.24V
- 40 uA to 100 mA operation
- Drop-in replaces any 1.24V shunt reference
- Low TC voltage reference
- Improved AC, DC performance compared to TLV431, 432 part types
- **RoHS compliant**

Pin Configuration



Pin Descriptions

Pin Name	Function
CATH	Output and supply terminal, must be greater than 1.2V for normal operation
REF	Input, nominally 1.24V in normal operation.
ANODE	Ground and Substrate

Absolute Maximum Ratings

Stress greater than those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These stress ratings only, and functional operation of the device at these or any conditions beyond those indicated under recommended Operating Conditions is not implied. Exposure to “Absolute Maximum Rating” for extended periods may affect device reliability. Use of standard ESD handling precautions is required.

Parameter	Value	Units
CATH Voltage	18	V
REF Current	3	mA
CATH, ANODE Currents	150	mA
Operating Junction Temperature	150	°C
Lead Temperature (soldering 10 seconds)	260	°C
Storage Temperature Range	-65 to +150	°C

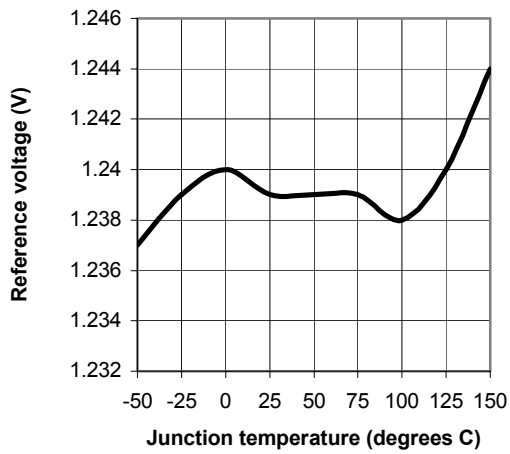
Electrical Specifications

Electrical characteristics are guaranteed over the full temperature range $-40^{\circ}\text{C} < T_j < 105^{\circ}\text{C}$ unless otherwise stated. Ambient temperature must be de-rated based upon power dissipation and package thermal characteristics.

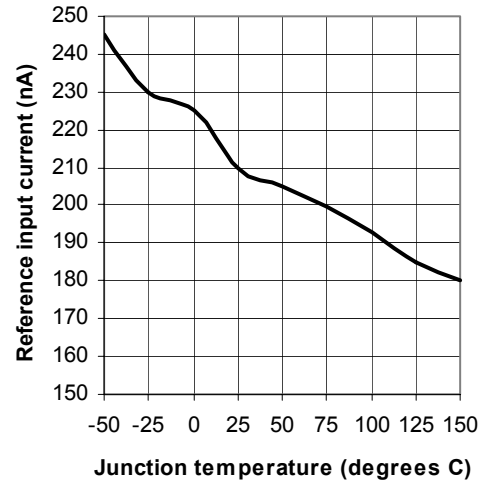
Symbol	Parameter	Conditions	Min	Typ	Max	Units	
V_{REF}	Reference Voltage	25°C; $V_{\text{REF}}=V_{\text{CATH}}$; $I_{\text{CATH}}=10\text{mA}$	0.5% option	1.234	1.240	1.246	V
			1.0% option	1.228	1.240	1.252	V
ΔV_{REF}	V_{REF} Temperature deviation	$-40^{\circ}\text{C} < T_j < 105^{\circ}\text{C}$.		4	12	mV	
$\frac{\Delta V_{\text{REF}}}{\Delta V_{\text{CATH}}}$	Ratio of V_{REF} Change to V_{CATH} Change (Line Reg; 1/gain)	$I_{\text{CATH}}=10\text{mA}$, $V_{\text{CATH}} = V_{\text{REF}}$ to 6V		0.3	1	mV/V	
I_{REF}	Reference input current	$I_{\text{CATH}}=10\text{mA}$		0.2	0.4	μA	
ΔI_{REF}	I_{REF} Temperature Deviation			0.04	0.2	μA	
$I_{\text{CATH}(\text{min})}$	Minimum Cathode Current			18	40	μA	
$I_{\text{CATH}(\text{OFF})}$	Off-State Cathode Current	$V_{\text{REF}}=0\text{V}$; $V_{\text{CATH}}=16\text{V}$			100	nA	
r_{CATH}	Dynamic Output Impedance	$I_{\text{CATH}}=0.1$ to 100mA $f \leq 1.0$ kHz		0.3	0.4	Ω	

Typical Performance Characteristics

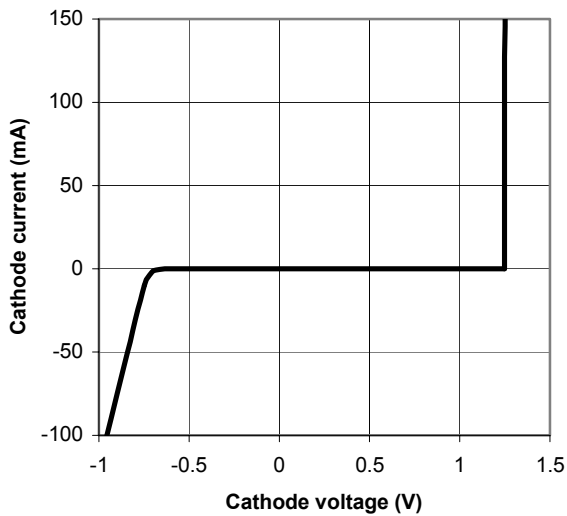
Reference voltage vs Junction temperature



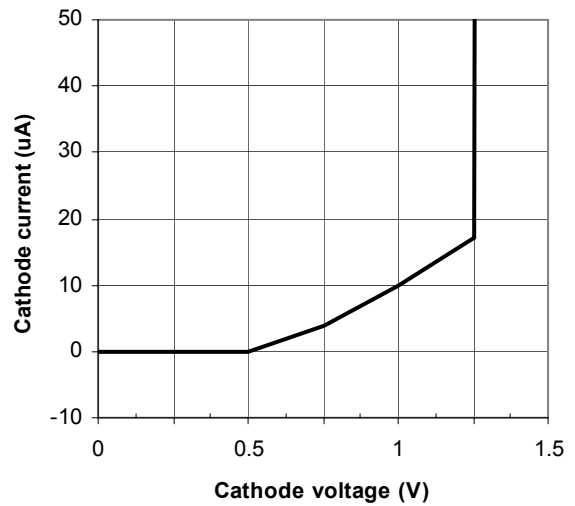
Reference input current vs junction temperature



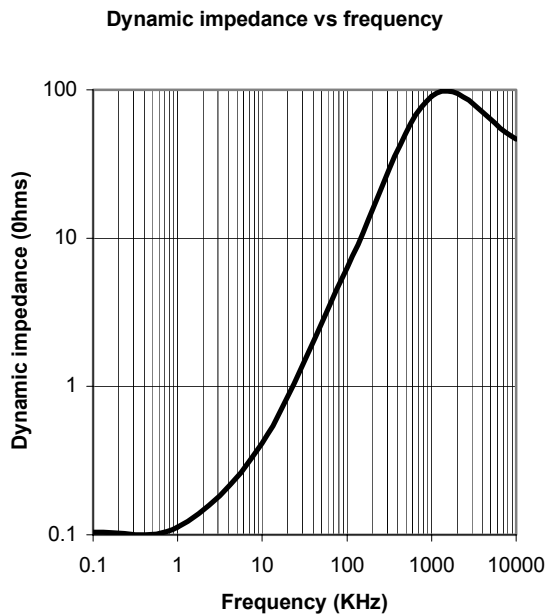
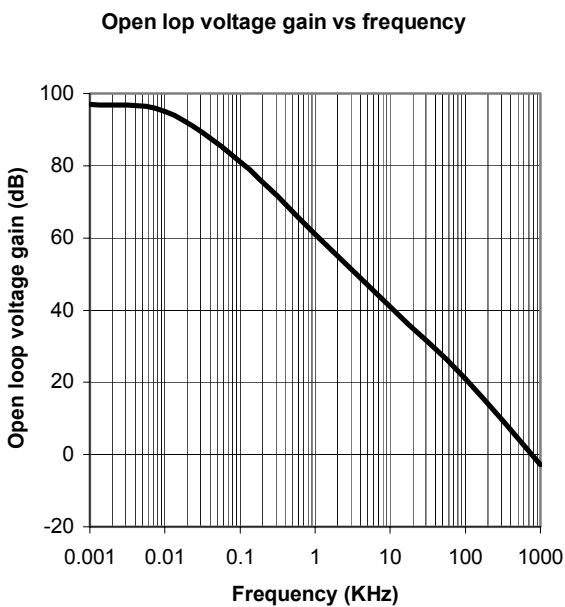
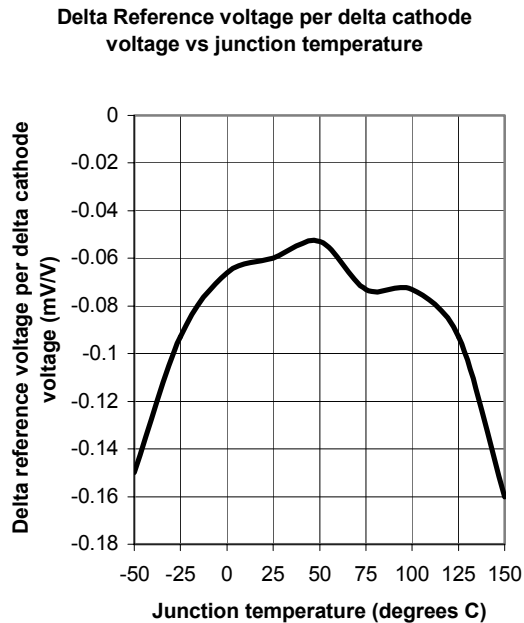
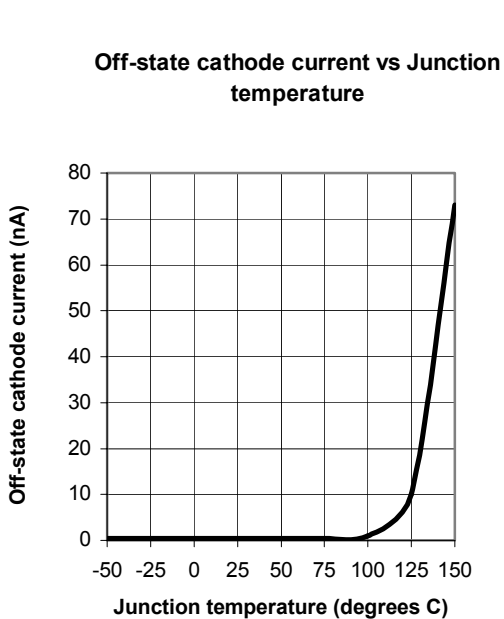
Cathode current vs Cathode voltage



Cathode current vs Cathode voltage

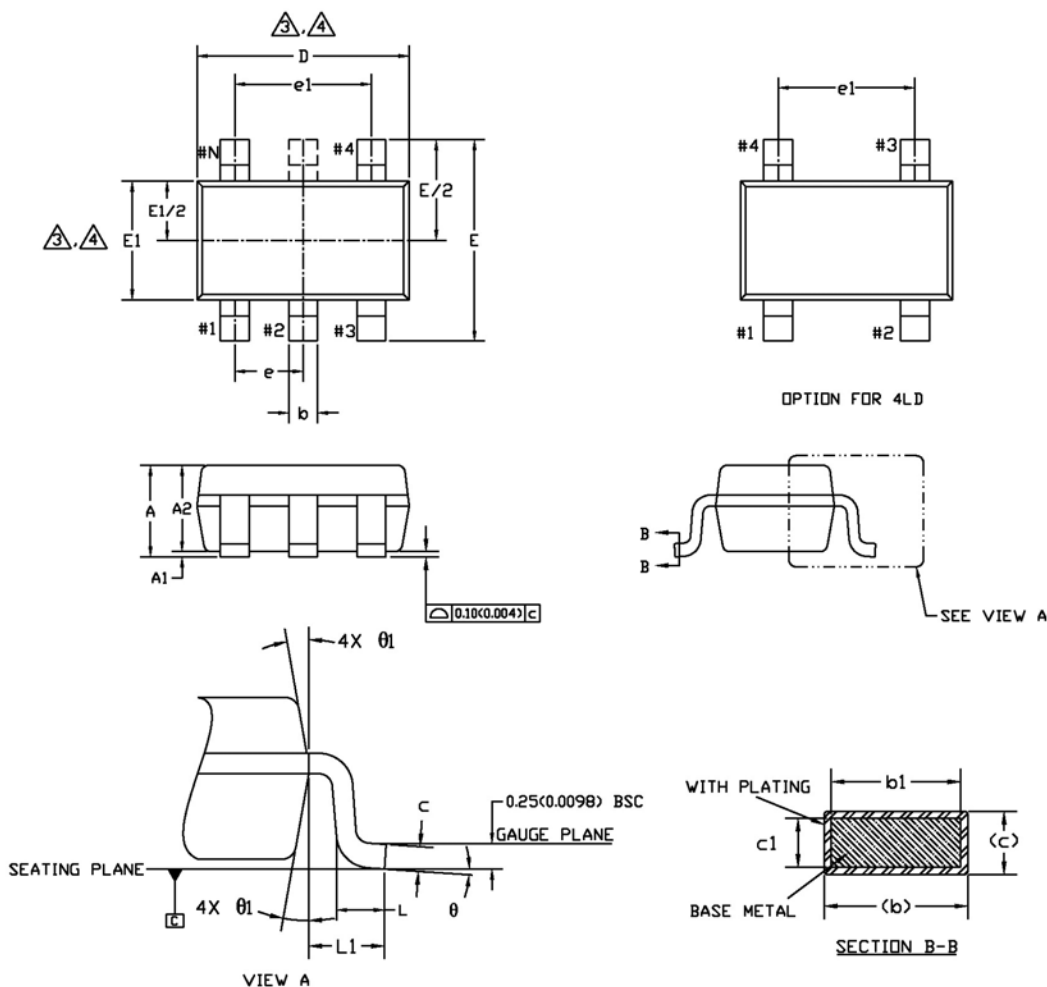


Typical Performance Characteristics (contd.)



Package Dimensions

SOT23-3, SOT23-4, SOT23-5, SOT23-6



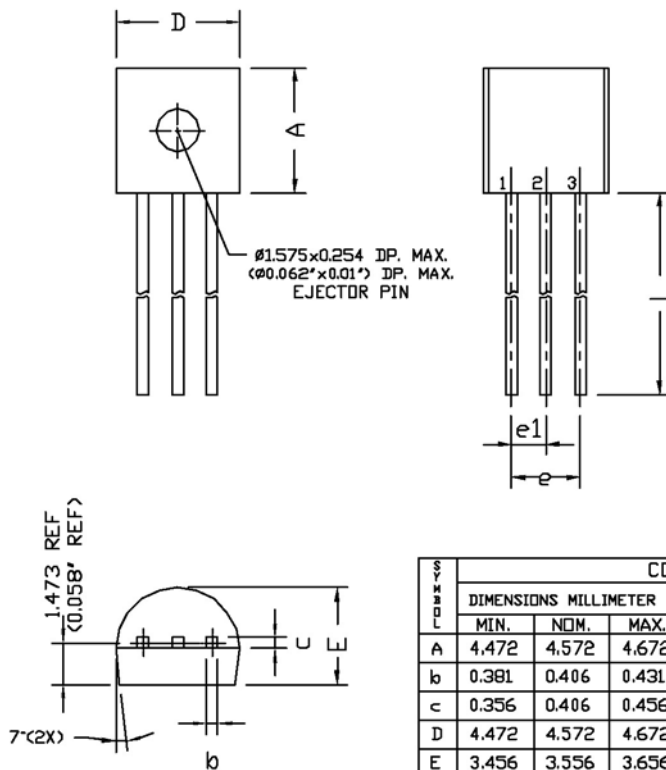
SYMBOL	COMMON					
	DIMENSIONS MILLIMETER			DIMENSIONS INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.20	1.30	1.40	0.047	0.051	0.055
A1	0.05	-	0.15	0.002	-	0.006
A2	0.90	1.15	1.30	0.035	0.045	0.051
b	0.35	-	0.50	0.013	-	0.020
b1	0.35	0.40	0.45	0.013	0.015	0.017
c	0.08	-	0.22	0.003	-	0.008
c1	0.08	0.13	0.20	0.003	0.005	0.007
D	2.90 BSC			0.114 BSC		
E	2.80 BSC			0.110 BSC		
E1	1.60 BSC			0.062 BSC		
e	0.95 BSC			0.037 BSC		
e1	1.90 BSC			0.074 BSC		
L	0.35	0.45	0.55	0.013	0.017	0.021
L1	0.60 REF.			0.023 REF.		
θ	0°	4°	8°	0°	4°	8°
θ1	10° TYP			10° TYP		

NOTE :

1. Dimensioning and tolerancing per ASME Y 14.5 M - 1994.
2. Dimensions are in millimeters. Converted inch dimension are not necessarily exact.
3. Dimension D does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 0.15 mm per side. Dimension E1 does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.15 mm per side.
4. Top package may be smaller than the bottom package. Dimension D and E1 are determined at the outermost extremes of the plastic body exclusive of mold flash gate burrs and interlead flash.
5. Terminal numbers are shown for reference only. Die is facing up for molding. Die is facing down for trim/form.

Package Dimensions

TO92-2, TO92-3



SYMBOL	COMMON					
	DIMENSIONS MILLIMETER			DIMENSIONS INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	4.472	4.572	4.672	0.176	0.180	0.184
b	0.381	0.406	0.431	0.015	0.016	0.017
c	0.356	0.406	0.456	0.014	0.016	0.018
D	4.472	4.572	4.672	0.176	0.180	0.184
E	3.456	3.556	3.656	0.136	0.140	0.144
e	2.413	2.540	2.667	0.095	0.100	0.105
e1	1.143	1.270	1.397	0.045	0.050	0.055
L	13.87	13.97	14.07	0.546	0.550	0.554

NOTES :

1. CONTROLLING DIMENSION : MILLIMETER. CONVERTED INCH DIMENSION ARE NOT NECESSARILY EXACT.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1973.
3. FOR 2 LEAD PACKAGE CENTER LEAD IS CLIPPED

Ordering Information

Device	Operating Tj	%Tol	PKG Type	VOUT	Wrap	Ordering Number
LDS431LP	-40C° ≤ 105C°	1.0	TO-92-3	1.24V	T&R	LDS431LBY-N3-12-TL
LDS431LP	-40C° ≤ 105C°	0.5	TO-92-3	1.24V	T&R	LDS431LBZ-N3-12-TL
LDS431LP	-40C° ≤ 105C°	1.0	SOT-23-3	1.24V	T&R	LDS431LBY-M3-12-TL
LDS431LP	-40C° ≤ 105C°	0.5	SOT-23-3	1.24V	T&R	LDS431LBZ-M3-12-TL

Note: Lead Free and RoHS compliant.

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